

SPECIFICATION FOR APPROVAL

COMMERCIALY AVAILABLE

ITEM: CERAMIC BAND PASS
PART NUMBER: CF-06000255

Revised 06/20/18 – Clarified Stop Band Performance

ISSUED	CHECKED	CHECKED	CHECKED
11/8/07 **	7/12/10 SW	7/12/2010 BF	
4/5/11 kn	4/19/2011 SRJ	4/20/2011 BF	4/20/2011 GL
06/20/18 ^(tg)			

FILTRONETICS Inc.

1. APPLICATION

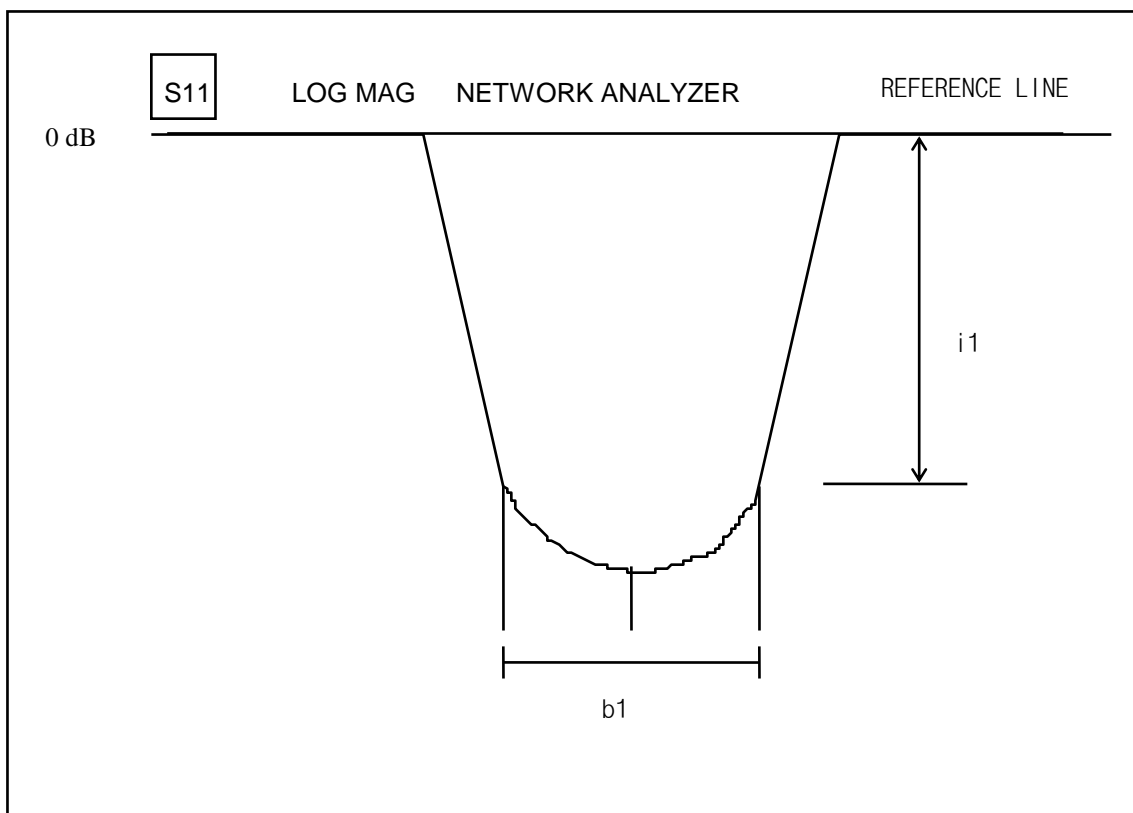
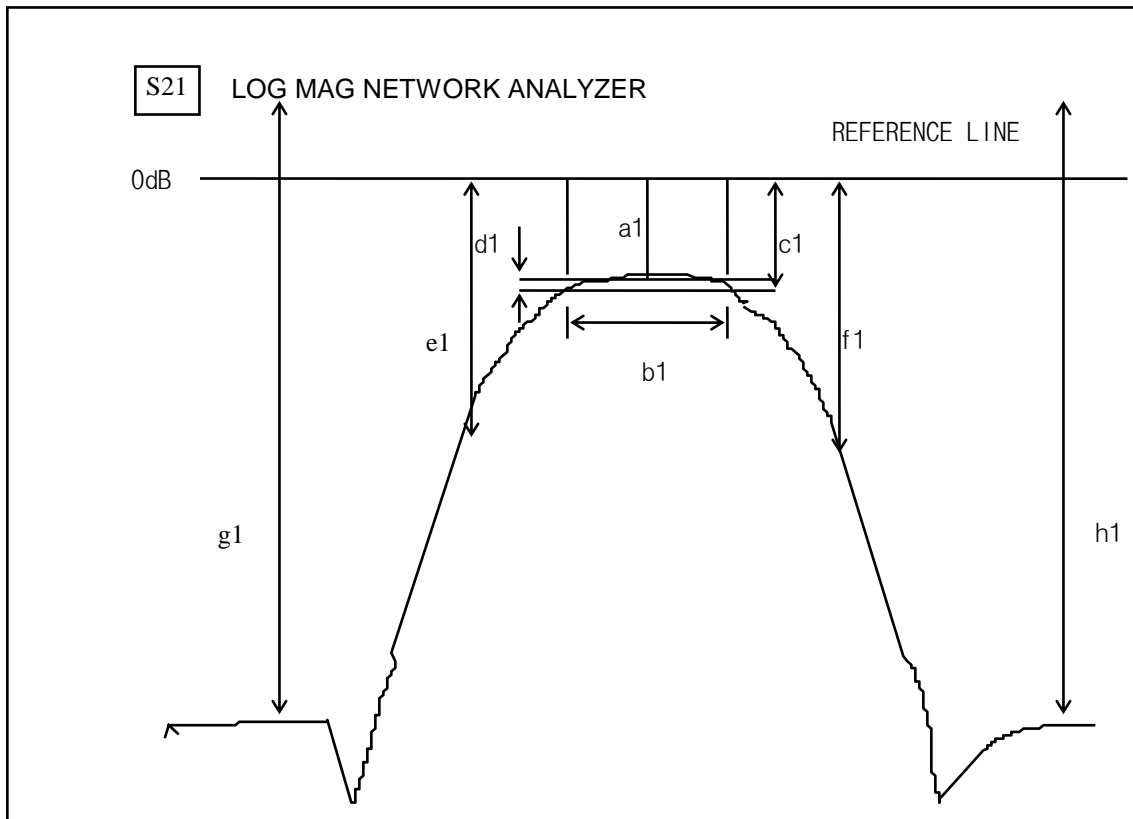
THIS SPECIFICATION APPLIES TO BAND PASS FILTER, USING DIELECTRIC RESONATORS.

2. PART NUMBER

PART NO	CF-06000255
PACKING	PLASTIC TRAY

3. SPECIFICATIONS

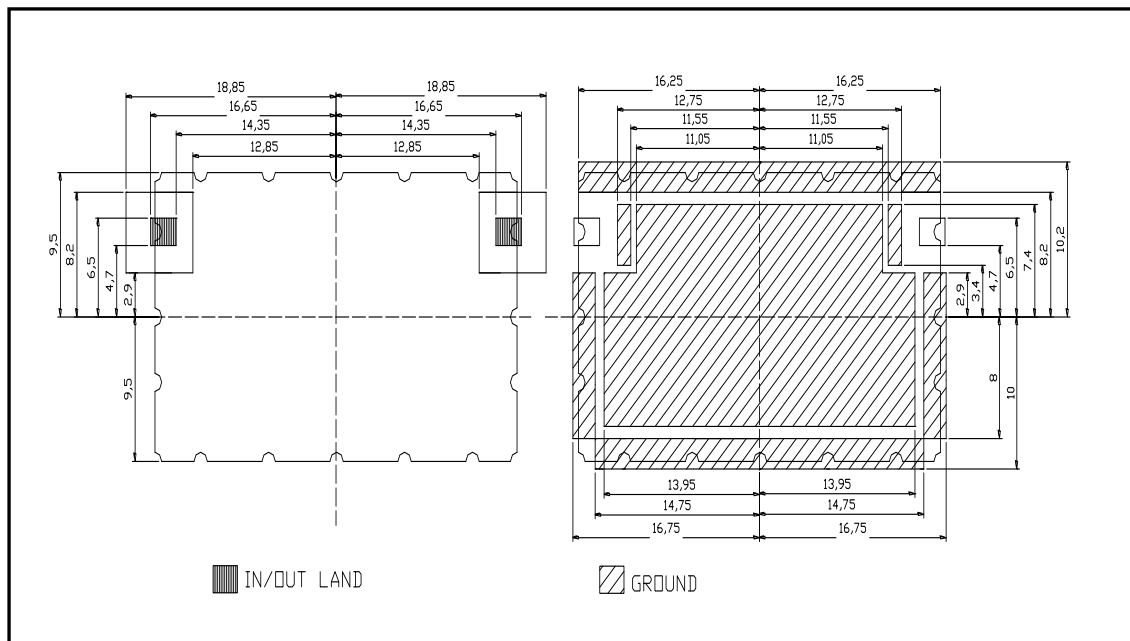
Center Frequency (F0)	a1	600 MHz	
Pass Band Width	b1	Fo +/-12.5 MHz	
Insertion Loss @ F0	c1	2.5 dB max	
Ripple in PB	d1	1.0 dB max	
Attenuation	F0 ±100 MHz	g1~h1	70dB Min
	F0 ± 200 MHz	g1~h1	70 dB Min
	At 480 MHz	g1~h1	65 dB Min
	DC ~ 500 MHz	g1~h1	65 dB Min
	700MHz ~ 1200 MHz	g1~h1	65 dB Min
Return Loss in PB	i1	16 dB min	
Impedance		50 Ohms	
Maximum Input Power		1 W (+30 dBm)	
Operating Temperature Range		-40°C to +70°C	



4. SPECIFICATION:

CHARACTERISTICS	DESCRIPTION	SPECIFICATION
CENTER FREQUENCY	THE MIDPOINT OF THROUGH BANDPASS FILTER PASSBAND, NORMALLY EXPRESSED AS THE ARITHMETIC MEAN OF THE -3 dB POINT. ALSO CALLED Fo.	3. SPECIFICATION
PASS BAND WIDTH	THE WIDTH OF THE PASSBAND OF A FILTER REFERENCED TO THE MINIMUM INSERTION LOSS POINT IN THE PASSBAND. THE PASSBAND OF A FILTER IS STATED AS -1.0 dB BANDWIDTH.	
INSERTION LOSS	THE LOSS OF THE FILTER, IN dB, MEASURED AT THE MAXIMUM LOSS POINT OF THE PASSBAND RELATIVE TO A THROUGH LINE (0 dB).	
ATTENUATION	REDUCTION OF RF POWER THROUGH A FILTER, MEASURED IN dB, AT DESIRED BAND RELATIVE TO LOSS OF FILTER AT CENTER FREQUENCY.	
PASSBAND RIPPLE	VARIATIONS IN LOSS IN THE PASSBAND OF THE FILTER, SUPERIMPOSED UPON THE FUNDAMENTAL SHAPE OF THE PASSBAND.	
V.S.W.R in PB	THE RATIO OF THE MAXIMUM VALUE OF A STANDING WAVE TO ITS MINIMUM VALUE, RELATED TO THE RETURN LOSS IN PASSBAND.	

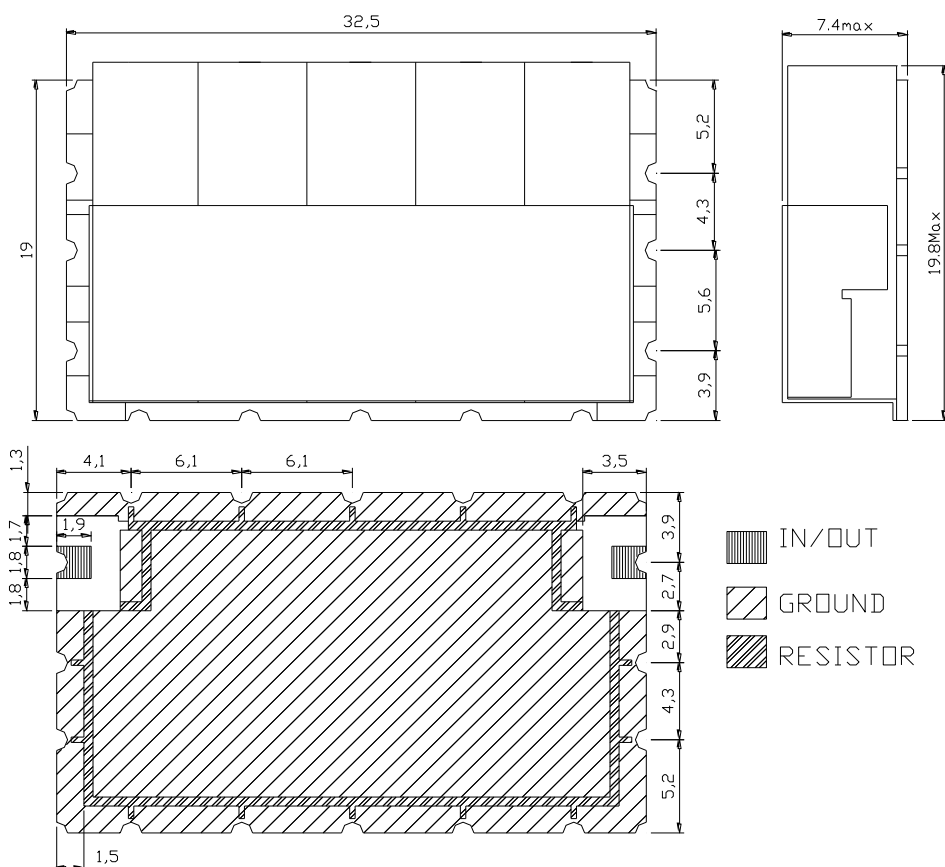
LAY OUT



5. DIMENSIONS:

UNIT: mm

TOLERANCE: +/- 0.5 mm

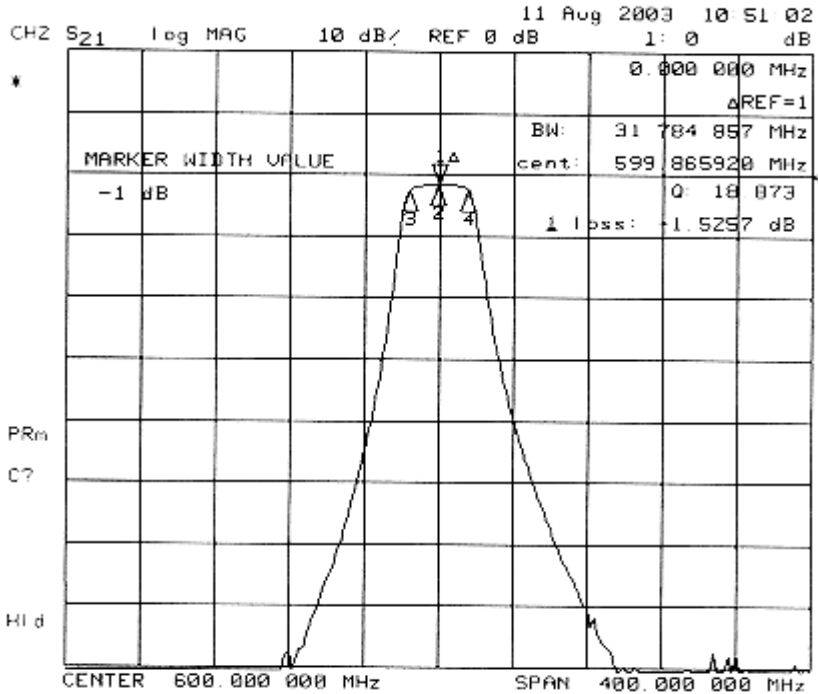
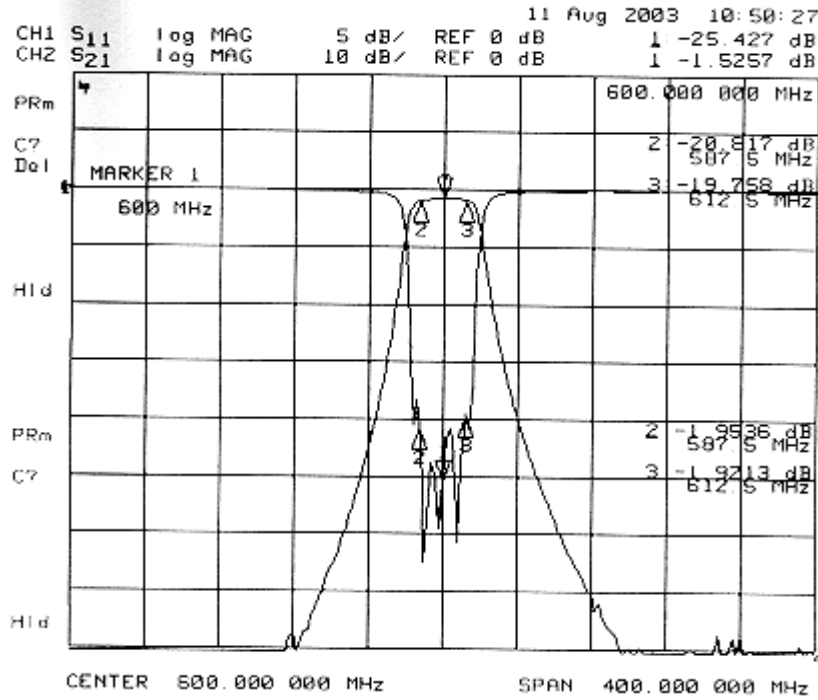


- 1. PCB
 - 1) MATERIAL : FR-4
 - 2) TERMINALS : Gold (Au) PLATED
- 2. CASE
 - 1) MATERIAL : Sn OR Ni PLATED

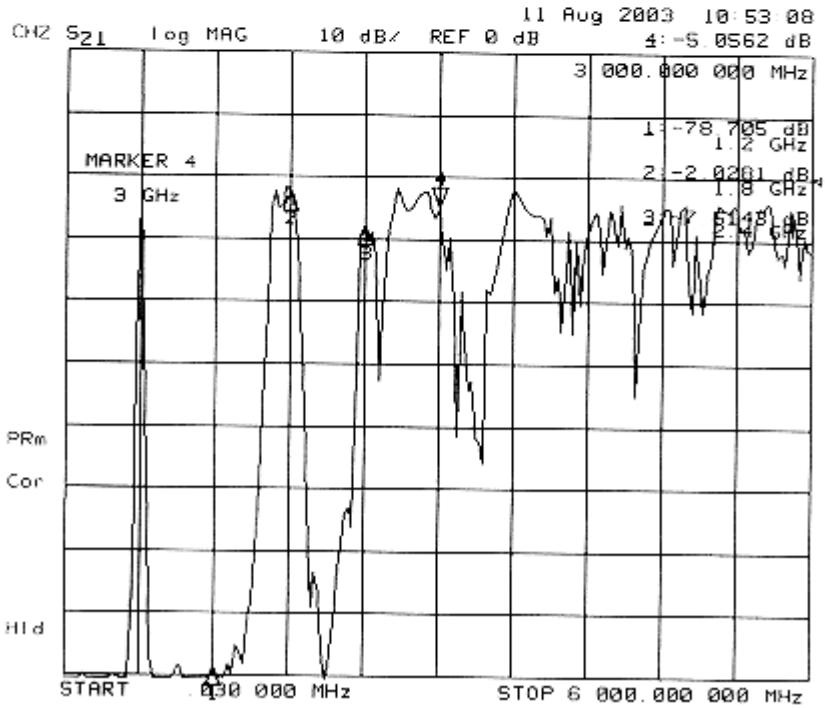
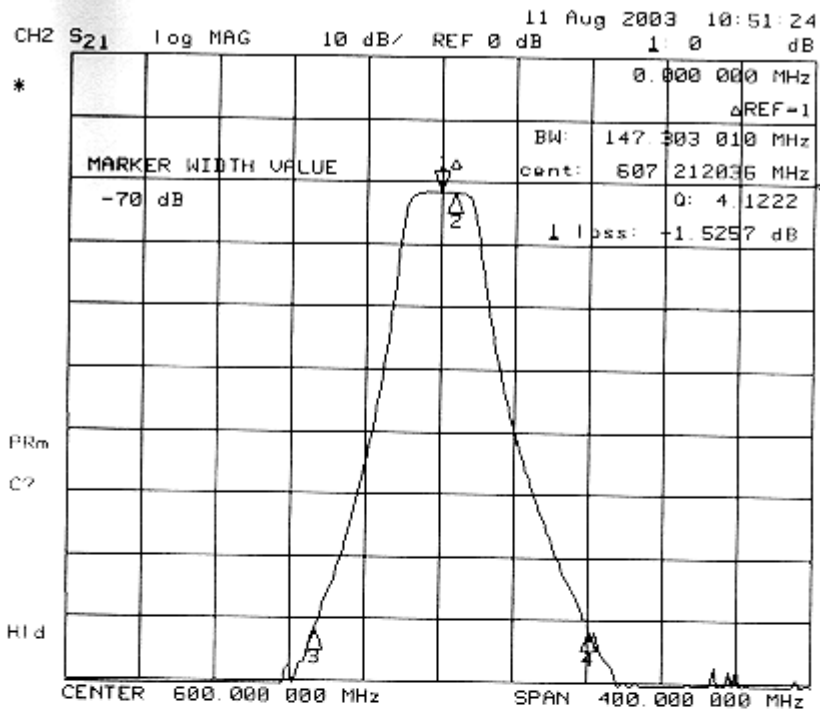
<p>Marking: CF-0600255 Date Code</p>

6. GRAPHS:

S21 vs. S11 (INSERTION LOSS, RETURN LOSS, 1 dB bandwidth)



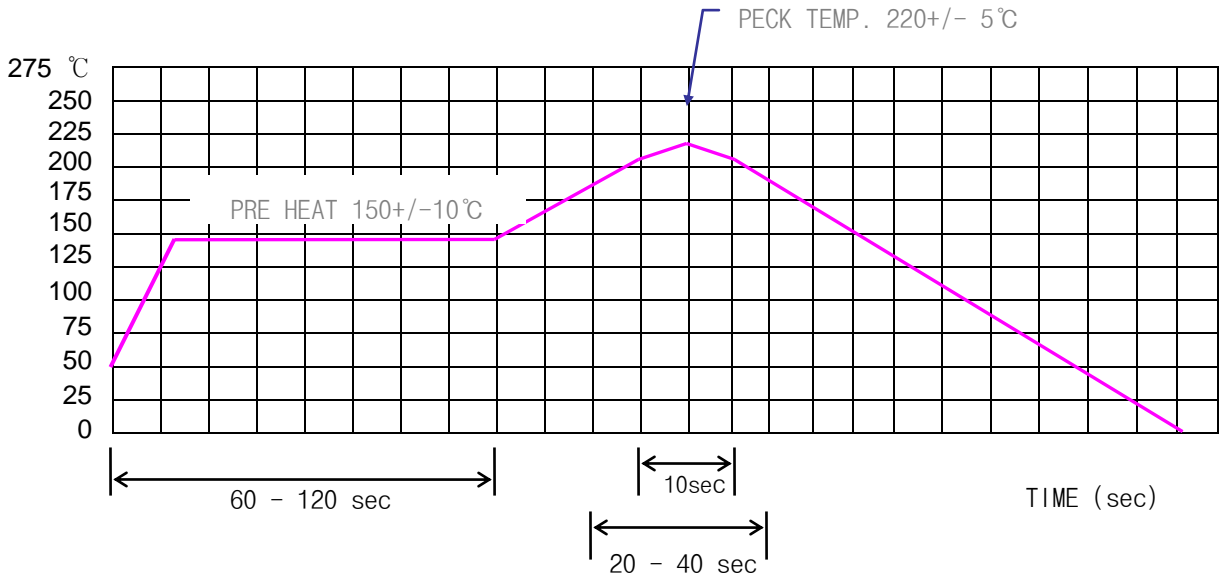
S21 (ATTENUATION, OUTBAND ATTENUATION)



7. RELIABILITY TEST AND CONDITIONS:

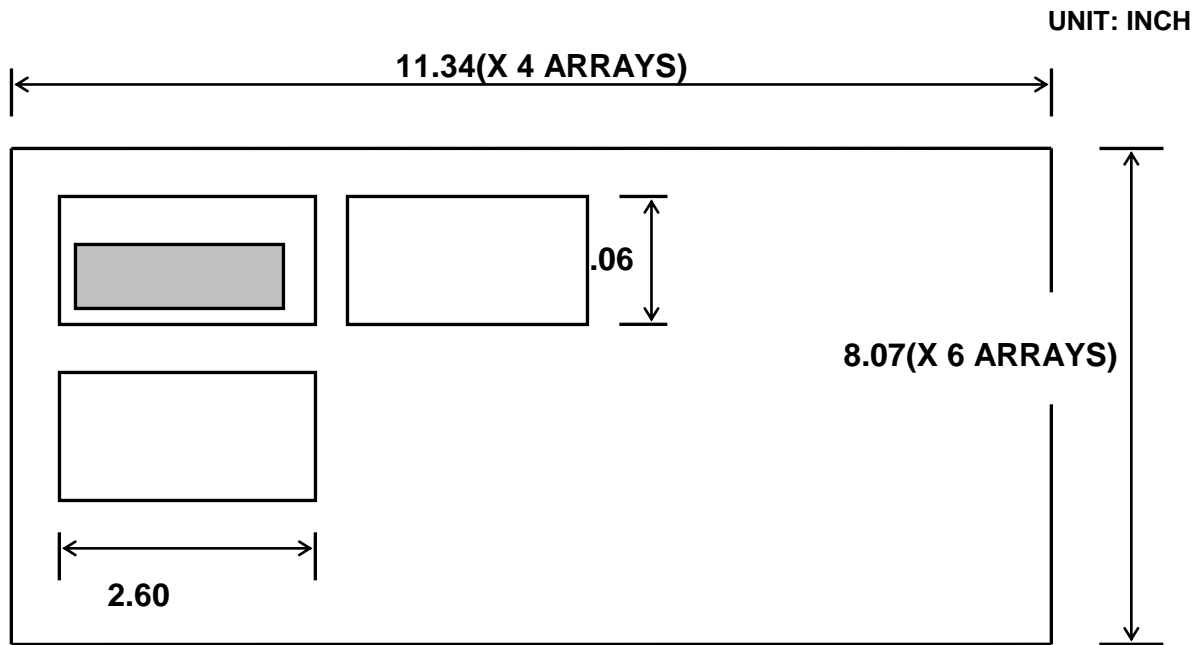
ITEM	TEST CONDITIONS	REQUIREMENTS
Resistance to solder heat	Preheat temperature : 120 to 150°C Preheat time : 1 to 1.5 min Solder temperature : 260 +/- 10°C Dipping time : 10 +/- 0.5 sec	No damage such as cracks should Be caused in chip element.
Solderability	Preheat temperature : 120 to 150°C Preheat time : 1 to 1.5 min Solder temperature : 235 +/- 5°C Dipping time : 5 +/- 1 sec	More than 80% of the terminal electrode shall be covered with new solder
Heat resistance (High-temperature load)	Temperature : 85 +/- 2°C Applied voltage : Rated voltage Applied current : Rated current Recovery : 1 to 2hrs of recovery under the standard condition after the removal from test chamber.	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Thermal shock (Temperature cycle)	Conditions for 1 cycle / Step 1 : + 85°C 15 min Step 2: - 30°C 15 min Number of cycle : 10	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Humidity resistance	Temperature : 40 +/- 2°C Humidity : 90 to 95% RH Duration : 96 +/- 5 hrs Recovery : 1 to 2hrs of recovery under the standard condition after the removal from test chamber.	No mechanical damage. After test, the device shall satisfy the specification in section 3.
Vibration	Frequency : 10 ~ 50 Hz Amplitude : 1.52mm (0.060 inches) Direction and time : X, Y and Z Directions for 30 min each.	No mechanical damage. After test, the device shall satisfy the specification in section 3.

8. REFLOW SOLDERING STANDARD CONDITIONS



9. PACKING DIMENSION

9. 1 PLASTIC TRAY



 : FILTER

- 1. MATERIAL: ABS
- 2. HEIGHT: 0.303 inch